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02/28/2006 RCOBB1 00000001 500310 10603764
01 FC:1251 120.00 DA

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02/28/2006 RCOBB1 00000001 500310 10603764
01 FC:1251 120.00 CR

DEP & REF



PATENT MAINTENANCE
DIVISION

PATENT

ATTORNEY DOCKET NO.: 053933-5045
2006 JUN 19 PM 3:50

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Bong-Suck KIM, et al.) Confirmation No.: 4495
Application No.: 10/603,764) Group Art Unit: 3729
Filed: June 26, 2003) Examinier: Phan, Thiem D.
For: METHOD FOR MANUFACTURING)
BUILT-UP PRINTED CIRCUIT)
BOARD WITH STACK TYPE)
VIA-HOLES)

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

REQUEST FOR REFUND UNDER 37 C.F.R. § 1.26(a)

This is a request for refund under 37 C.F.R. § 1.26(a) for fees charged to our Deposit Account No. 50-0310 in excess of that which was required. On February 17, 2006, an Amendment was filed which included a petition for a one month extension of time. The Amendment Transmittal Form authorized a charge of \$120.00 to Deposit Account No. 50-0310 for the extension of time fees. (See Attachment A.) However, the above-identified application was charged twice for the one month extension of time. (See Attachment B.)

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Application No.: 10/603,764
Page 2

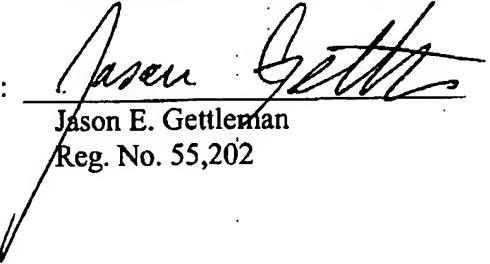
Accordingly a refund in the amount of \$120.00 is hereby requested. Please credit Deposit Account No. 50-0310 in the amount of \$120.00 and indicate that the credit is for our Attorney Docket 053933-5045-US.

Respectfully submitted,

MORGAN, LEWIS & BOCKIUS LLP

Dated: June 15, 2006

By:


Jason E. Gettleman
Reg. No. 55,202

CUSTOMER NO. 09629
MORGAN, LEWIS & BOCKIUS LLP
1111 Pennsylvania Avenue, N.W.
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Telephone: (202) 739-3000
Facsimile: (202) 739-3001



PLEASE STAMP AND RETURN TO SHOW RECEIPT OF:

In re Application of:)
Bong-Suck KIM, et al.) Confirmation No.: 4495
Application No.: 10/603,764) Group Art Unit No.: 3729
Filed: June 26, 2003) Examiner: Phan, Thiem D.
For: METHOD FOR MANUFACTURING) Mail Stop Amendment
BUILT-UP PRINTED CIRCUIT)
BOARD WITH STACK TYPE)
VIA-HOLES (as currently amended))

1. Amendment Transmittal Form
2. Amendment
3. Authorization to Charge Deposit Acct. 50-0310 in the amount of \$120.00 for Extension of Time fee

Dated: February 17, 2006
Attorney Docket No.: 053933-5045
JEG/jp



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Bong-Suck KIM, et al.) Confirmation No.: 4495
Application No.: 10/603,764) Group Art Unit: 3729
Filed: June 26, 2003) Examiner: Phan, Thiem D.
For: METHOD FOR MANUFACTURING) Mail Stop Amendment
BUILT-UP PRINTED CIRCUIT)
BOARD WITH STACK TYPE)
VIA-HOLES (as currently amended))

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Window, MAIL STOP AMENDMENT
Randolph Building
Alexandria, VA 22314

Sir:

AMENDMENT TRANSMITTAL FORM

1. Transmitted herewith is an Amendment in response to Non-Final Office Action dated October 17, 2005, the period for response due January 17, 2006 has been extended one month through February 17, 2006, by the attached petition for extension of time and appropriate fee, please amend the above-identified application as follows.
2. Additional papers enclosed:

Information Disclosure Statement
 Form PTO-1449, _____ references included
 Citations
 Declaration of Biological Deposit
 Others

3. Extension of Time

The proceedings herein are for a patent application and the provisions of 37 C.F.R. § 1.136(a) apply.

Applicants believe that no extension of time is required. However, this conditional petition is being made to provide for the possibility that applicants have inadvertently overlooked the need for a petition and fee for extension of time.

Applicants petition for an extension of time, the fees for which are set out in 37 C.F.R. § 1.17(a), for the total number of months checked below:

Total Months <u>Requested</u>	Fee for <u>Extension</u>	[Fee for Small Entity]
<input checked="" type="checkbox"/> one month	\$ 120.00	\$ 60.00
<input type="checkbox"/> two months	\$ 450.00	\$ 225.00
<input type="checkbox"/> three months	\$ 1,020.00	\$ 510.00
<input type="checkbox"/> four months	\$ 1,590.00	\$ 795.00

Extension of time fee due with this request: \$120.00

If an additional extension of time is required, please consider this a Petition therefor.

An extension for _____ months has already been secured and the fee paid therefor of \$_____ is deducted from the total fee due for the total months of extension now requested.

4. Constructive Petition

EXCEPT for issue fees payable under 37 C.F.R. § 1.18, the Commissioner is hereby authorized by this paper to charge any additional fees during the entire pendency of this application including fees due under 37 C.F.R. §§ 1.16 and 1.17 which may be required, including any required extension of time fees, or credit any overpayment to Deposit Account 50-0310. This paragraph is intended to be a CONSTRUCTIVE PETITION FOR EXTENSION OF TIME in accordance with 37 C.F.R. § 1.136(a)(3).

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5. Fee Calculation (37 C.F.R. §1.16)

CLAIMS AS AMENDED						
	Claims Remaining After Amendment		Highest No. Previously Paid	Present Extra	at Rate of	Total Fees
Total Claims (37 C.F.R. §1.16(c))	10	minus	25	0	x \$50 each=	+ \$ -0-
Independent Claims (37 C.F.R. §1.16(b))	1	minus	3	1	x \$200 each=	+ \$ 0.00-
[] First presentation of Multiple dependent claim(s)					\$360.00	+ \$
SUB-TOTAL =						\$0.00
Reduction by ½ for filing by a small entity						- \$
TOTAL FEE =						\$0.00

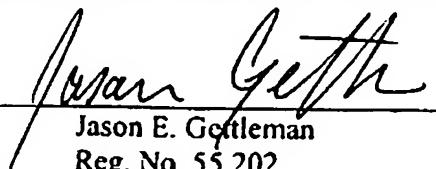
6. Fee Payment

- No fee is to be paid at this time.
- The Commissioner is hereby authorized to charge \$120.00 (extension of time fee) to Deposit Account No. 50-0310.
- The Commissioner is hereby authorized to charge any additional fees which may be required, including fees due under 37 C.F.R. §§ 1.16 and 1.17, or credit any overpayment to Deposit Account 50-0310.

Respectfully submitted,

MORGAN, LEWIS & BOCKIUS LLP

Dated: February 17, 2006

By: 
Jason E. Gentleman
Reg. No. 55,202

CUSTOMER NO. 09629
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PATENT
ATTORNEY DOCKET NO.: 053933-5045

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of:

Bong-Suck KIM et al.) Confirmation No. 4495

Application No.: 10/603,764) Group Art Unit: 3729

Filed: June 26, 2003) Examiner: T. Phan

For: METHOD FOR MANUFACTURING)
BUILT-UP PRINTED CIRCUIT)
BOARD WITH STACK TYPE)
VIA-HOLES (as currently amended)) **Mail Stop Amendment**

Commissioner for Patents
U.S. Patent and Trademark Office
Mail Stop Amendment
Alexandria, VA 22314

Sir:

AMENDMENT

In response to the Office Action dated October 17, 2005, the period for response due January 17, 2006 has been extended one month through February 17, 2006, by the attached petition for extension of time and appropriate fee, please amend the above-identified application as follows.

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U.S. Patent Application No. 10/603,764
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IN THE TITLE:

Please replace the Title of the Invention with the following amended Title:

METHOD FOR MANUFACTURING BUILT-UP PRINTED CIRCUIT BOARD WITH
STACKED STACK TYPE VIA-HOLES AND METHOD FOR MANUFACTURING
THE SAME

ATTORNEY DOCKET NO.: 053933-5045
U.S. Patent Application No. 10/603,764
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IN THE SPECIFICATION

At page 1, immediately before the heading "BACKGROUND OF THE INVENTION" please insert the following new paragraph:

-- The present application claims priority to Korean Patent Application No. 2002-79216,
filed in Korea on December 12, 2002.--

IN THE CLAIMS:

Claim 1 (Currently Amended): A method for manufacturing a built-up printed circuit board with stack type via-holes, comprising the steps of:

- (a) forming a first via-hole through a first copper layer of a first laminated copper sheet by means of a laser drill to expose a second copper layer of the first laminated copper sheet;
- (b) forming a first plated layer on the first via-hole and on the first laminated copper sheet;
- (c) filling the first plated via-hole with a via-hole filling material;
- (d) grinding the top surface of the first via-hole filled with the via-hole filling material to level the first via-hole;
- (e) forming a second plated layer on the first filled via-hole and the first plated layer to cover the first filled via-hole; and
- (f) disposing a second laminated copper sheet on the second plated layer, and repeating the steps (a) to (e) to form a second via-hole.

Claim 2 (Original): The method as set forth in claim 1, wherein the laser is a CO₂ laser or an Nd-YAG laser.

Claim 3 (Original): The method as set forth in claim 1, wherein the first and second plated layers are formed by means of P/N plating (CAP plating).

Claim 4 (Original): The method as set forth in claim 1, wherein the via-hole filling material is filled in the via-hole by a general screen printing process.

Claim 5 (Original): The method as set forth in claim 4, wherein a portion of a poly screen corresponding to the via-hole is opened so that the via-hole filling material passes through the opened portion to fill only the via-hole during the screen printing.

Claim 6 (Original): The method as set forth in claim 1, wherein the via-hole filling material is liquefied insulating resin.

Claim 7 (Original): The method as set forth in claim 1, wherein the via-hole filling material is conductive paste.

Claim 8 (Original): The method as set forth in claim 7, wherein the conductive paste is copper paste or silver paste.

Claim 9 (Original): The method as set forth in claim 1, wherein a viscosity of the via-hole filling material is not more than 100 dPa.s.

Claim 10 (Original): The method as set forth in claim 1, wherein the grinding step is carried out by a grinder made of ceramic buff, scotch buff, highcut buff, or belt.

Claim 11 (Withdrawn): A method for manufacturing a built-up printed circuit board with stack type via-holes, comprising the steps of:

- (a) forming a first via-hole through a first laminated copper sheet by means of a laser drill;
- (b) forming a first plated layer on the first via-hole and on the first laminated copper sheet;
- (c) filling the first plated via-hole with a via-hole filling material;
- (d) grinding the top surface of the first via-hole filled with the via-hole filling material to level the first via-hole;
- (e) forming a second plated layer on the first leveled via-hole and the first laminated copper sheet to cover the first leveled via-hole;
- (f) disposing a second laminated copper sheet on the second plated layer,
- (g) forming a second via-hole through the second laminated copper sheet by means of the laser drill;
- (h) filling the second via-hole with another via-hole filling material;
- (i) grinding the top surface of the second via-hole filled with the via-hole filling material to level the second via-hole; and

(j) forming a third plated layer on the second leveled via-hole and the second laminated copper sheet to cover the second leveled via-hole, and forming a circuit pattern on the third plated layer.

Claim 12 (Withdrawn): The method as set forth in claim 11, wherein a viscosity of the via-hole filling material is not more than 100 dPa.s.

Claim 13 (Withdrawn): The method as set forth in claim 11, wherein the filling step of filling the via-hole with the via-hole filling material is carried out using a general screen printing machine.

Claim 14 (Withdrawn): The method as set forth in claim 13, wherein the screen printing machine has a screen of not more than 250 mesh of a poly or stainless steel (SUS) sheet.

Claim 15 (Withdrawn): The method as set forth in claim 13, wherein the screen printing machine has a rubber squeegee spreading speed of not more than 150 mm/sec.

Claim 16 (Withdrawn): The method as set forth in claim 11, further comprising:
firstly drying the printed circuit board at a low temperature of 60 to 80 °C for 15 to 30 minutes; and

secondly drying the printed circuit board at a high temperature of 140 to 160 °C for 30 to 60 minutes,

wherein the first and second drying steps are carried out after the filling step of filling the via-hole with the via-hole filling material.

Claim 17 (Withdrawn): The method as set forth in claim 11, wherein the via-hole formed by the laser drill has a diameter of 50 µm to 200 µm.

Claim 18 (Withdrawn): A built-up printed circuit board with stack type via-holes, comprising:

- a plurality of first via-holes formed through a first laminated copper sheet by means of a laser drill;
- a first plated layer formed on the first via-holes and the first laminated copper sheet;
- a filling material filled in each of the first plated via-holes;
- a second plated layer formed on the first filled via-holes and the first plated layer to cover the first filled via-holes;
- a plurality of second laminated copper sheets disposed on the second plated layer, respectively; and
- a plurality of second via-holes formed through the second laminated copper sheets by means of the laser drill.

Claim 19 (Withdrawn): The board as set forth in claim 18, wherein the laser is a CO₂ laser or an Nd-YAG laser.

Claim 20 (Withdrawn): The board as set forth in claim 18, wherein the first and second plated layers are formed by means of P/N plating (CAP plating).

Claim 21 (Withdrawn): The board as set forth in claim 18, wherein the via-hole filling material is filled in each of the via-hole by a general screen printing process.

Claim 22 (Withdrawn): The board as set forth in claim 21, wherein portions of a poly screen corresponding to the via-holes are opened so that the via-hole filling material passes through each of the opened portions to fill only the via-holes during the screen printing.

Claim 23 (Withdrawn): The board as set forth in claim 18, wherein the via-hole filling material is liquefied insulating resin.

Claim 24 (Withdrawn): The board as set forth in claim 18, wherein the via-hole filling material is conductive paste.

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Page 10

Claim 25 (Withdrawn): The board as set forth in claim 24, wherein the conductive paste is copper paste or silver paste.

REMARKS

Summary of the Office Action

Claims 1-8 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Mizumoto et al. (US 5,956,843) in view of Asai et al. (US 6,240,636) or vice versa.

Claim 9 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Mizumoto et al. in view of Asai et al. and further view of Ogura et al. (US 6,660,811).

Claim 10 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Mizumoto et al. ('843) in view of Asai et al. and further view of Mizumoto et al. (US 5,883,335).

Summary of the Response to the Office Action

Applicants have amended claim 1 to further define the invention. In addition, Applicants have amended the Specification and the Title of the Invention to correct minor informalities. Accordingly, claims 1-25 are presently pending with claims 11-25 being apparently withdrawn from consideration.

Election Response

Applicants respectfully request clarification regarding the claims presently being withdrawn from consideration by the Examiner. Specifically, the Restriction Requirement dated August 12, 2005 alleges that three different groups of invention exist in the present application. The Requirement identified a first Group I (claims 1-17) and a second Group II (claims 18-25), wherein the first Group I further allegedly included a first sub-Group IA (claims 1-10) and a second sub-Group IB (claims 11-17). Accordingly, Applicants submitted a Response to the

Requirement on September 12, 2005 electing the first sub-Group IA, corresponding to claims 1-10.

The Office Action dated October 17, 2005 fails to identify or acknowledge that claims 18-25 have been withdrawn from consideration by the Examiner. Specifically, the Office Action indicates that claims 11-17 have been withdrawn from further consideration pursuant to 37 CFR 1.142(b), but provided no indication regarding the status of claims 18-25. For purpose of Applicants' present Response, claims 18-25 are believed to have been withdrawn by the Examiner although no explicit indication has been provided by the Examiner. Thus, if claims 18-25 have not been withdrawn by the Examiner, Applicants respectfully request that the next Office Action not be made final in order to provide Applicants with a fair opportunity to address any rejections that may be applied against any of claims 18-25.

Accordingly, Applicants respectfully request clarification in the next Communication from the USPTO regarding the status of claims 18-25.

The Rejection of Claims 1-10 under 35 U.S.C. § 103(a)

Claims 1-8 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Mizumoto et al. (US 5,956,843) in view of Asai et al. (US 6,240,636) or vice versa, claim 9 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Mizumoto et al. in view of Asai et al. and further view of Ogura et al. (US 6,660,811), and claim 10 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Mizumoto et al. ('843) in view of Asai et al. and further view of Mizumoto et al. (US 5,883,335). Applicants respectfully traverse these rejections for at least the following reasons.

Independent claim 1, as amended, recites a method of manufacturing a built-up printed circuit board with stack type via holes including, in part, a step of "forming a first via-hole through a first copper layer of a first laminated copper sheet by means of a laser drill to expose a second copper layer of the first laminated copper sheet." In contrast to Applicants' claimed invention, the dielectric resin film 110 disclosed by Mizumoto et al. ('843) fails to include "first and second copper layers extending along opposing sides of the first laminated copper sheet," as required by amended independent claim 1, and hence dependent claims 2-10. Specifically, Applicants respectfully assert that the method disclosed by Mizumoto et al. ('843) explicitly requires forming via holes through a dielectric material having a single land 520. Thus, Applicants respectfully assert that Mizumoto et al. ('843) fails to teach or suggest the combination of features recited by amended independent claim 1, and hence dependent claims 2-10.

In addition, Applicants respectfully assert that Asai et al., Ogura et al., and Mizumoto et al. ('335) fail to remedy the deficiencies of Mizumoto et al., as detailed above. Moreover, Applicants respectfully assert that Asai et al., Ogura et al., and Mizumoto et al. ('335), whether taken singly or combined, cannot remedy the deficiencies of Mizumoto et al. since none of Asai et al., Ogura et al., and Mizumoto et al. ('335) teach or suggest a method of manufacturing a built-up printed circuit board with stack type via holes including, in part, a step of "forming a first via-hole through a first copper layer of a first laminated copper sheet by means of a laser drill to expose a second copper layer of the first laminated copper sheet," as required by amended independent claim 1, and hence dependent claims 2-10.

With regard to the Office Action's allegation that "[i]t is a mere matter of design choice to have a portion of a poly screen corresponding to the via-hole opened so that the via-hole filling material passes through the opened portion to fill all the via-hole during the screen printing," Applicants respectfully disagree. Applicants respectfully assert that the prior art of record fails to teach or suggest that Applicants' claimed method is "merely a design choice." Specifically, none of Mizumoto et al. ('843), Asai et al., Ogura et al., and Mizumoto et al. ('335) teach the interchangeability or desirability to use screen printing instead of spot filling. Accordingly, Applicants respectfully assert that the Office Action fails to establish a *prima facie* case of obviousness with regard to at least amended independent claim 1.

With regard to the Office Action's allegation that "it appears that the invention would perform well with spot-filling the via-hole since it is known in the art that only the via-hole is spot-filled by covering the outer portions of the via hole (Mizumoto et al. ('843), col. 5, lines 37-41)," Applicants respectfully disagree. Applicants respectfully assert that the different methods disclosed by Mizumoto et al. ('843) all require subsequent processing of the filling material to remove excess filling material. Specifically, since Mizumoto et al. ('843) explicitly discloses that the filling material more than fills the via holes, the different methods disclosed by Mizumoto et al. ('843) all require steps of removing the excess filling material. Accordingly, Applicants respectfully assert that Mizumoto et al. ('843) fails to provide any proper motivation with which to substitute the spot-filling method with Applicants' claimed method, as recited by amended independent claim 1.

Furthermore, Applicants respectfully assert that the conclusion set forth by the Office Action is neither taught nor suggest by any of the prior art of record. Specifically, none of Mizumoto et al. ('843), Asai et al., Ogura et al., and Mizumoto et al. ('335) teach that it is well known to interchange the spot-filling method disclosed by Mizumoto et al. ('843) with Applicants' claimed method. Accordingly, Applicants respectfully assert that since any combination of Mizumoto et al. ('843), Asai et al., Ogura et al., and Mizumoto et al. ('335) fails to teach or suggest that substituting the spot-filling method of Mizumoto et al. ('843) with Applicants' claimed invention is well known, a mere design choice, or conventional, then the Office Action fails to establish a *prima facie* case of obviousness with regard to Applicants' claimed invention.

For the above reasons, Applicants respectfully assert that the rejections under 35 U.S.C. §103(a) should be withdrawn because none of the applied prior art references, whether taken individually or in combination, teach or suggest the novel combination of features clearly recited in amended independent claim 1, and hence dependent claims 2-10.

CONCLUSION

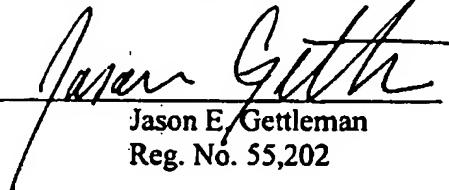
In view of the foregoing, Applicants respectfully request reconsideration and the timely allowance of the pending claims. Should the Examiner feel that there are any issues outstanding after consideration of the response, the Examiner is invited to contact the Applicants' undersigned representative to expedite prosecution.

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If there are any other fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-0310. If a fee is required for an extension of time under 37 C.F.R. § 1.136 not accounted for above, such an extension is requested and the fee should also be charged to our Deposit Account.

Respectfully submitted,

MORGAN, LEWIS & BOCKIUS LLP

By: 

Jason E. Gentleman
Reg. No. 55,202

Dated: February 17, 2006

CUSTOMER NO. 09629
MORGAN, LEWIS & BOCKIUS LLP
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Washington, D.C. 20004
Telephone: (202) 739-3000

*O I P E IAP80
JUN 15 2006
U.S. PATENT & TRADEMARK OFFICE*

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02/27 757	09757559		8021	\$40.00	\$121,016.00
02/27 758	10074757		8021	\$40.00	\$120,976.00
02/27 759	60509922		8021	\$40.00	\$120,936.00
02/28 1	10603764	053933-5045	1251	\$120.00	\$120,816.00 ✓
02/28 1	10894252	060142-5001-01	1460	\$130.00	\$120,688.00
02/28 10	11358340	18638-04-5082	8021	\$40.00	\$120,646.00
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02/28 108	10026941	049128-5029	1801	\$790.00	\$117,246.00
02/28 109	10026941	049128-5029	1253	\$570.00	\$116,676.00
02/28 130	60738848	51092-5024	1052	\$50.00	\$116,626.00
02/28 153	10749238	11038-120-999	1501	\$1,400.00	\$115,226.00
02/28 154	10749238	11038-120-999	1504	\$300.00	\$114,926.00
02/28 155	10749238	11038-120-999	8001	\$3.00	\$114,923.00

02/22 34	10915471	042715-5014	8001	\$12.00	\$109,546.00
02/22 34	11300155	060949-5021	1051	\$130.00	\$109,416.00
02/22 35	09671953	2307O-099120	2501	\$700.00	\$108,716.00
02/22 36	09671953	2307O-099120	8001	\$36.00	\$108,680.00
02/22 40	10186191	057040-5008	2253	\$510.00	\$108,170.00
02/22 43	10179888	040894-5797	1202	\$50.00	\$108,120.00
02/22 44	10179888	040894-5797	1201	\$200.00	\$107,920.00
02/22 59	10704811	053933-5056	1251	\$120.00	\$107,800.00
02/22 60	11273262	040894-7349	1011	\$300.00	\$107,500.00
02/22 61	11273262	040894-7349	1111	\$500.00	\$107,000.00
02/22 62	11273262	040894-7349	1311	\$200.00	\$106,800.00
02/22 63	11273262	040894-7349	1051	\$130.00	\$106,670.00
02/22 76	10495551	040894-7034	1201	\$400.00	\$106,270.00
02/22 77	10603764	053933-5045	1251	\$120.00	\$106,150.00✓
02/22 118	11233492	52555-5028	1011	\$300.00	\$105,850.00
02/22 119	11233492	52555-5028	1111	\$500.00	\$105,350.00
02/22 120	11233492	52555-5028	1311	\$200.00	\$105,150.00
02/22 121	11233492	52555-5028	1051	\$130.00	\$105,020.00
02/22 122	11233492	52555-5028	1253	\$1,020.00	\$104,000.00
02/22 213	11262206	060949-5003	1251	\$120.00	\$103,880.00
02/22 214	11262206	060949-5003	1051	\$130.00	\$103,750.00
02/22 216	5798160	56949-5001	2552	\$1,150.00	\$102,600.00
02/22 246	10747235	OKI 407	1501	\$1,400.00	\$101,200.00
02/22 247	10747235	OKI 407	1504	\$300.00	\$100,900.00
02/22 248	10747235	OKI 407	8001	\$3.00	\$100,897.00
02/22 272	11356859	063538-5002	2011	\$150.00	\$100,747.00
02/22 273	11356859	063538-5002	2111	\$250.00	\$100,497.00
02/22 274	11356859	063538-5002	2311	\$100.00	\$100,397.00
02/22 280	10541059	60809-5083-US	8021	\$40.00	\$100,357.00
02/22 293	10541059	60809-5083-US	8021	\$40.00	\$100,317.00
02/22 460	10523604	056258-0000	1617	\$130.00	\$100,187.00
02/22 461	10523604	056258-0000	8021	\$40.00	\$100,147.00
02/23 1	REPLENISHMENT		9204	-\$20,439.00	\$120,586.00
02/23 1	10938102	015114-074700US	1201	\$200.00	\$120,386.00
02/23 1	09435168	1899-001	1201	\$200.00	\$120,186.00
02/23 1	10289185	16866-007410	1201	\$200.00	\$119,986.00
02/23 1	10882082	056751-5002	1806	\$180.00	\$119,806.00
02/23 1	REPLENISHMENT		9204	-\$14,270.00	\$134,076.00
02/23 1	10240658	056291-5116	1806	\$180.00	\$133,896.00
02/23 2	10938102	015114-074700US	1202	\$100.00	\$133,796.00
02/23 2	10882082	056751-5002	2202	\$200.00	\$133,596.00
02/23 4	10331884	11037-065-99	1201	\$200.00	\$133,396.00
02/23 16	6349142		2551	\$450.00	\$132,946.00
02/23 17	6349142		2554	\$65.00	\$132,881.00
02/23 42	60725894	040853-01-5175-P1 (JSM)	2085	\$250.00	\$132,631.00
02/23 43	60774655	060912-5026-PR3	1005	\$200.00	\$132,431.00
02/23 77	10467887		1253	\$1,020.00	\$131,411.00
02/23 78	11354007	040894-7410	8021	\$40.00	\$131,371.00
02/23 81	11354001	040894-7405	8021	\$40.00	\$131,331.00
02/23 82	11354002	040894-7407	8021	\$40.00	\$131,291.00
02/23 83	11354009	040894-7411	8021	\$40.00	\$131,251.00
02/23 88	11354010	040894-7409	8021	\$40.00	\$131,211.00